

## **IN THE SPECIFICATION**

This revised paragraph [0015], including markings to show the changes, will replace the previous version:

**[0015]** After one or more dice are fabricated on a wafer, a protective layer is applied 102 to the wafer. Referring now to Figure 2, a top view of a fabricated wafer 200 is illustrated according to one embodiment of the present invention. During fabrication, a plurality of chips or dice 202 may have been formed on the wafer 200. The words “chip” and “die” are used interchangeably in this document. Each chip or die 202 may comprise microelectronic circuitry or devices. For example, each die 202 may comprise a microprocessor in an embodiment. In other embodiments, the protective layer 302 ~~102~~ may be applied to a single chip 202 that is not connected to other chips 202 on a wafer.